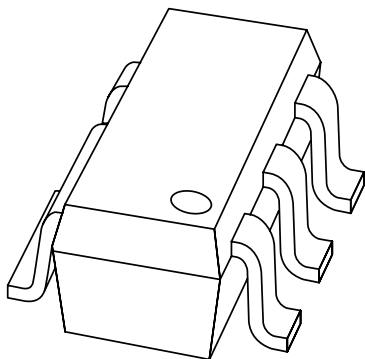


DATA SHEET



BGA2031 MMIC variable gain amplifier

Preliminary specification
Supersedes data of 1999 Feb 26

1999 Jul 23

MMIC variable gain amplifier

BGA2031

FEATURES

- High gain
- Excellent adjacent channel power rejection
- Small SMD package
- Low dissipation.

APPLICATIONS

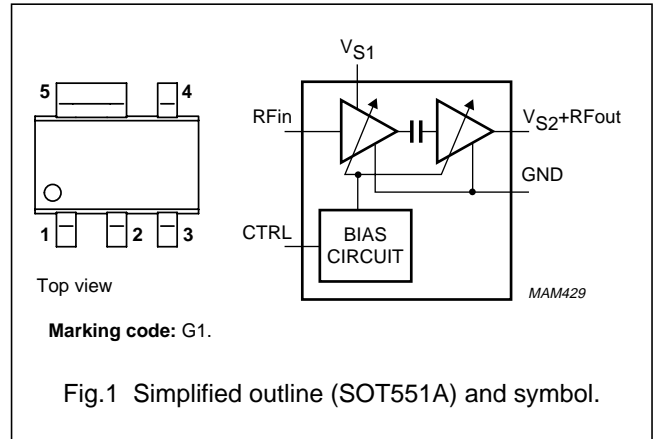
- General purpose variable gain amplifier for low voltage and medium power
- Driver for power amplifiers in systems that require good linearity, such as CDMA, both cellular band (850 MHz) and PCS (1.9 GHz). This is because of the high output power and good linearity.

DESCRIPTION

Silicon Monolithic Microwave Integrated Circuit (MMIC) 2 stage variable gain amplifier in double polysilicon technology in a 5-pin SOT551A plastic SMD package for low voltage medium power applications.

PINNING

PIN	DESCRIPTION
1	RF in
2	CTRL
3	V _{S1}
4	V _{S2} + RF out
5	GND



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{S1} , V _{S2}	supply voltages		3.6	4.1	V
I _S	supply current into pin 3 + pin 4	V _{CTRL} = 0	0	–	μA
		V _{CTRL} = 2.7 V; V _S = 3.6 V	51	63	mA
		V _{CTRL} = 2.4 V; V _S = 3 V	30	37	mA
P _L	load power	at 1 dB gain compression point; f = 1.9 GHz	13.5	–	dBm
ACPR	adjacent channel power rejection	f = 1.9 GHz; P _L = 12 dBm	48	–	dBc
		f = 836 MHz; P _L = 8 dBm	55	–	dBc
G _p	power gain	f = 1.9 GHz; P _L = 12 dBm	26	–	dB
		f = 836 MHz; P _L = 8 dBm	27	–	dB
ΔG	gain control range	f = 836 MHz; P _L = 8 dBm	70	–	dB

MMIC variable gain amplifier

BGA2031

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_S	DC supply voltage		–	4.2	V
I_{CTRL}	control current	$V_{CTRL} = 2.7\text{ V}$; $V_{S1} = 4.2\text{ V}$; $V_{S2} = 4.2\text{ V}$	–	1.2	mA
I_{S1}	current into pin 3	$V_{S1} = 4.2\text{ V}$	–	27	mA
I_{S2}	current into pin 4	$V_{S2} = 4.2\text{ V}$	–	50	mA
P_D	drive power		–	tbf	dBm
P_{tot}	total power dissipation	$T_s \leq 90\text{ °C}$	–	280	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–	150	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to solder point	$P_{tot} = 280\text{ mW}$; $T_s \leq 90\text{ °C}$	215	K/W

MMIC variable gain amplifier

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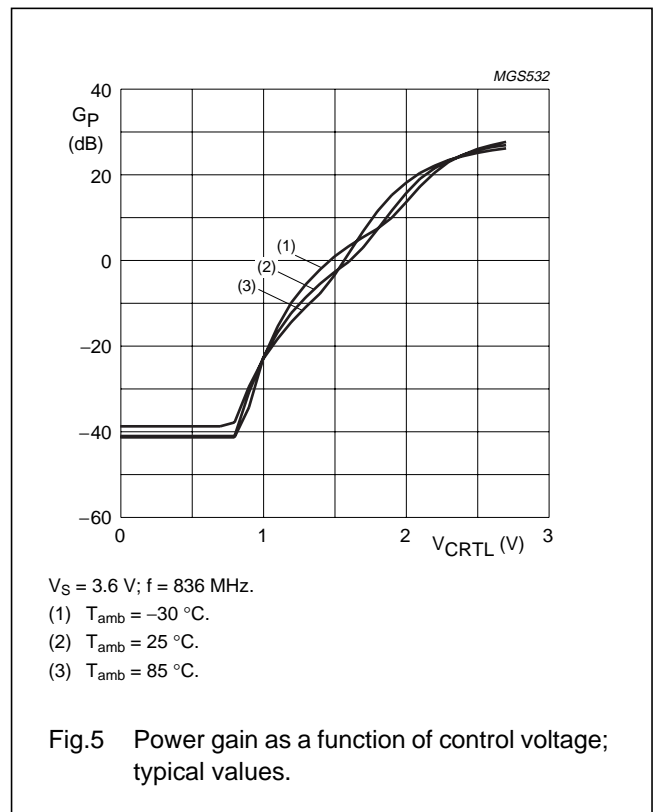
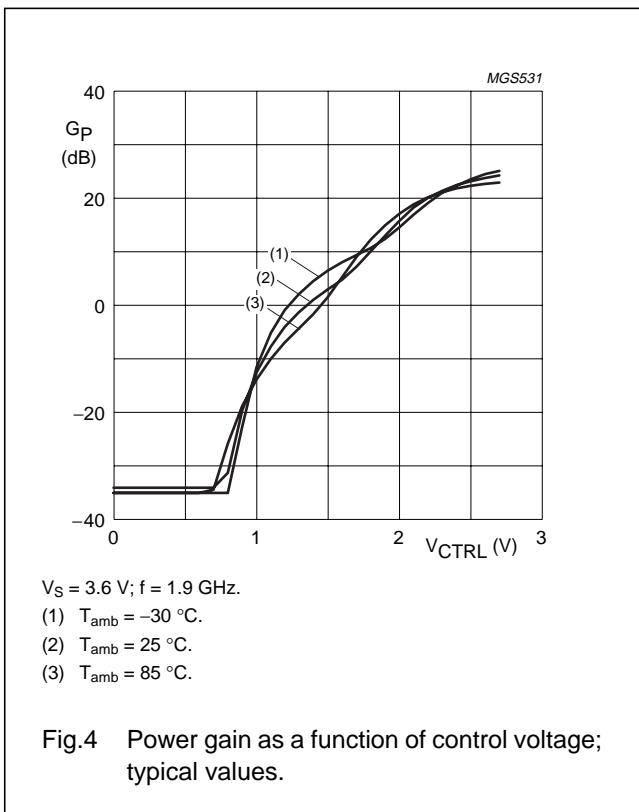
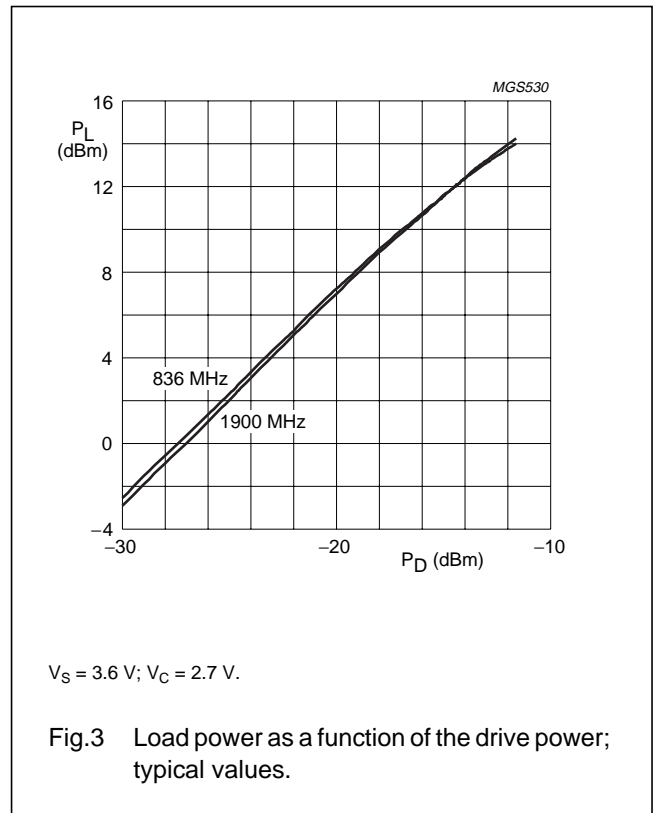
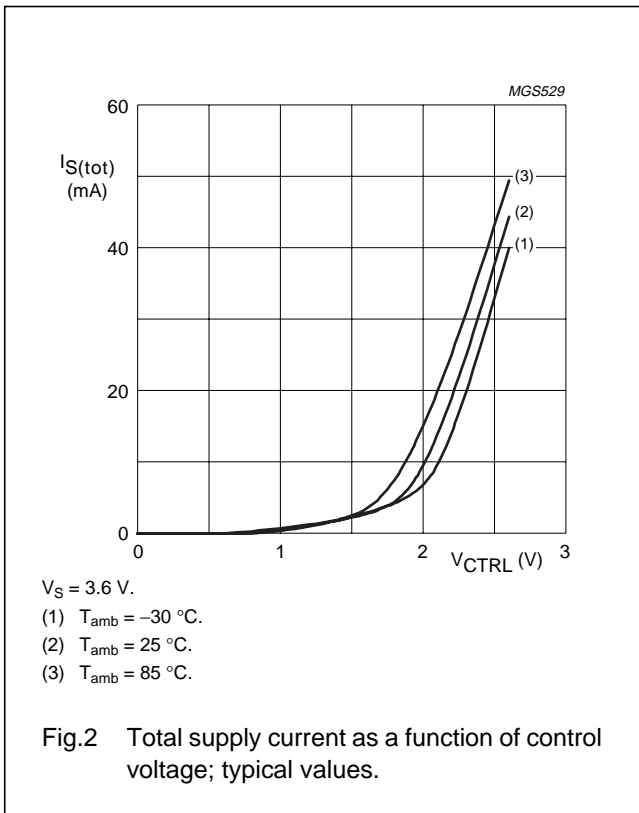
CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$; $Z_S = Z_L = 50\ \Omega$; $V_S = 3.6\text{ V}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f	frequency range		800	–	2500	MHz
V_{S1}, V_{S2}	supply voltages		2.7	3.6	4.1	V
I_S	supply current (in pin 3 + pin 4)	$V_{CTRL} = 0$	–	0	10	μA
		$V_{CTRL} = 2.7\text{ V}$; $V_S = 3.6\text{ V}$	39	51	63	mA
		$V_{CTRL} = 2.4\text{ V}$; $V_S = 3\text{ V}$	23	30	37	mA
I_{CTRL}	control current	$V_{CTRL} = 2.7\text{ V}$	0.7	0.92	1.1	mA
f = 1900 MHz						
f	frequency range		1850	–	1950	MHz
G_P	power gain	$V_{CTRL} = 2.7\text{ V}$; $P_L = 12\text{ dBm}$	–	26	–	dB
ΔG	gain control range	$0 < V_{CTRL} < 2.7\text{ V}$	–	61	–	dB
G_{CS}	gain control slope	middle of ΔG	–	38	–	dB/V
ACPR	adjacent channel power rejection	$\pm 1.23\text{ MHz}$ offset; $BW_{ACP} = 30\text{ kHz}$; $BW_{carrier} = 1.23\text{ MHz}$; $P_L = 10\text{ dBm}$	–	48	–	dBc
		$\pm 1.98\text{ MHz}$ offset; $BW_{ACP} = 30\text{ kHz}$; $BW_{carrier} = 1.23\text{ MHz}$; $P_L = 10\text{ dBm}$	–	67	–	dBc
P_L	load power	at 1 dB gain compression point	–	13.5	–	dBm
P_N	noise power	in CDMA receive band (1895 – 1955 MHz)	–	tbf	–	dBm/Hz
$V_{SWR_{IN}}$	input VSWR	$V_{CTRL} = 2.7\text{ V}$	–	1:3.5	–	
$V_{SWR_{OUT}}$	output VSWR	$V_{CTRL} = 2.7\text{ V}$	–	1:1.6	–	
f = 836 MHz						
f	frequency range		824	–	849	MHz
G_P	power gain	$V_{CTRL} = 2.7\text{ V}$; $P_L = 8\text{ dBm}$	–	27	–	dB
ΔG	gain control range	$0 < V_{CTRL} < 2.7\text{ V}$	–	70	–	dB
G_{CS}	gain control slope	middle of ΔG	–	40	–	dB/V
ACPR	adjacent channel power rejection	$\pm 885\text{ kHz}$ offset; $BW_{ACP} = 30\text{ kHz}$; $BW_{carrier} = 1.23\text{ MHz}$; $P_L = 8\text{ dBm}$	–	55	–	dBc
		$\pm 1.98\text{ MHz}$ offset; $BW_{ACP} = 30\text{ kHz}$; $BW_{carrier} = 1.23\text{ MHz}$; $P_L = 8\text{ dBm}$	–	69	–	dBc
P_L	load power	at 1 dB gain compression point	–	12	–	dBm
P_N	noise power	in CDMA receive band (869 to 894 MHz)	–	tbf	–	dBm/Hz
$V_{SWR_{IN}}$	input VSWR	$V_{CTRL} = 2.7\text{ V}$	–	1:2	–	
$V_{SWR_{OUT}}$	output VSWR	$V_{CTRL} = 2.7\text{ V}$	–	1:1.7	–	

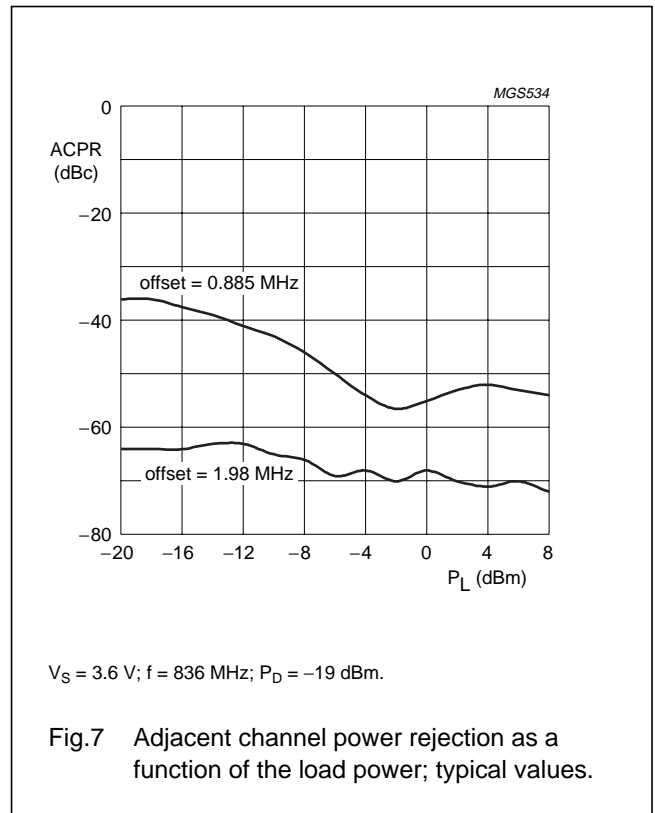
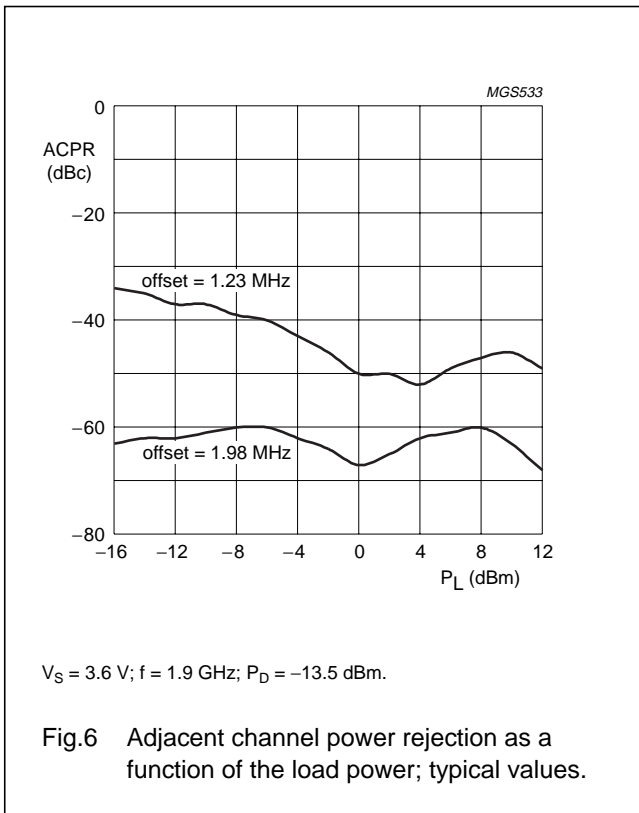
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MMIC variable gain amplifier

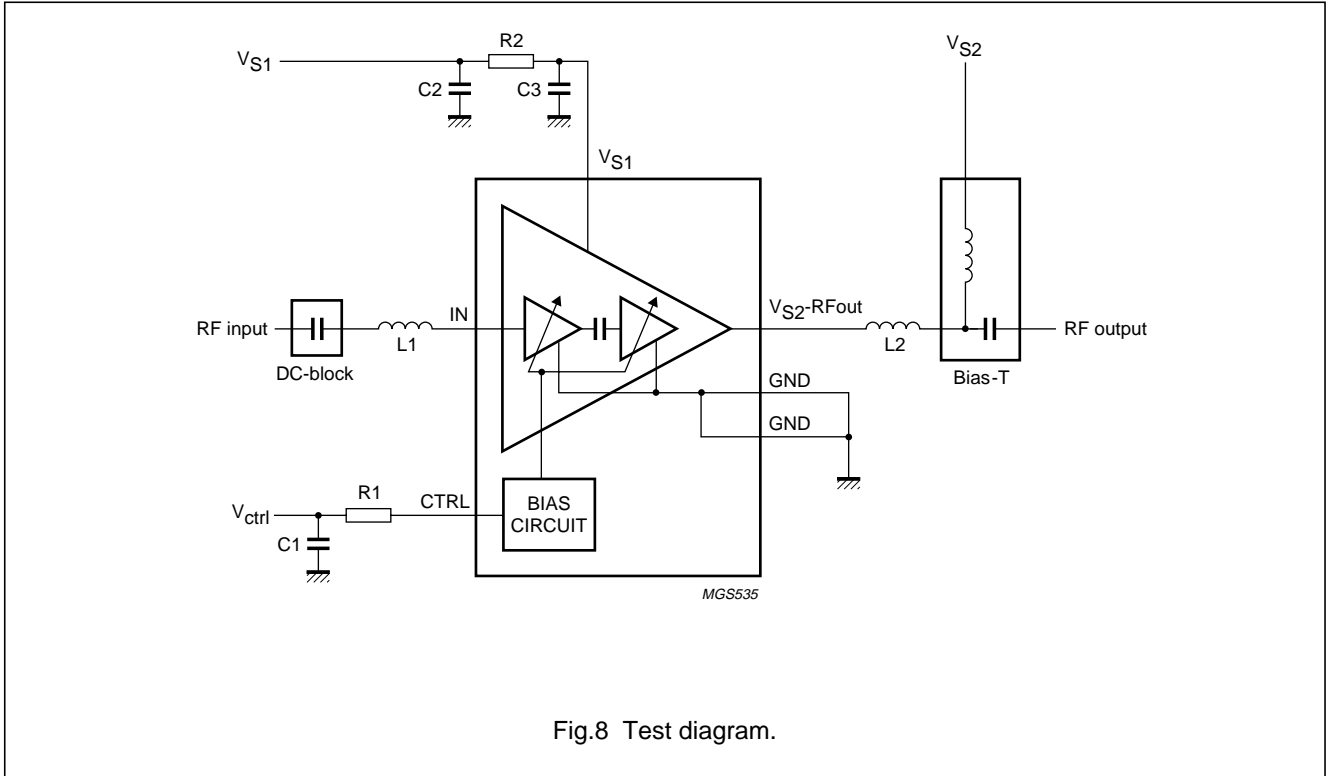
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MMIC variable gain amplifier

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ELECTRICAL BLOCK DIAGRAM



List of components (see Fig.8)

COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.
C1	multilayer ceramic chip capacitor	10 nF	0603	tbf
C2	multilayer ceramic chip capacitor	22 nF	0603	tbf
C3	multilayer ceramic chip capacitor	1.5 nF	0603	tbf
L1, L2	stripline; note 1	50 Ω		tbf
R1	SMD resistor	22 Ω; 0.16 W	0603	tbf
R2	SMD resistor	2.4 Ω; 0.16 W	0603	tbf

Note

1. The striplines are on a gold plated double copper-clad printed-circuit board ($\epsilon_r = 6.15$), board thickness = 0.64 mm, copper thickness = 35 μm , gold thickness = 5 μm .

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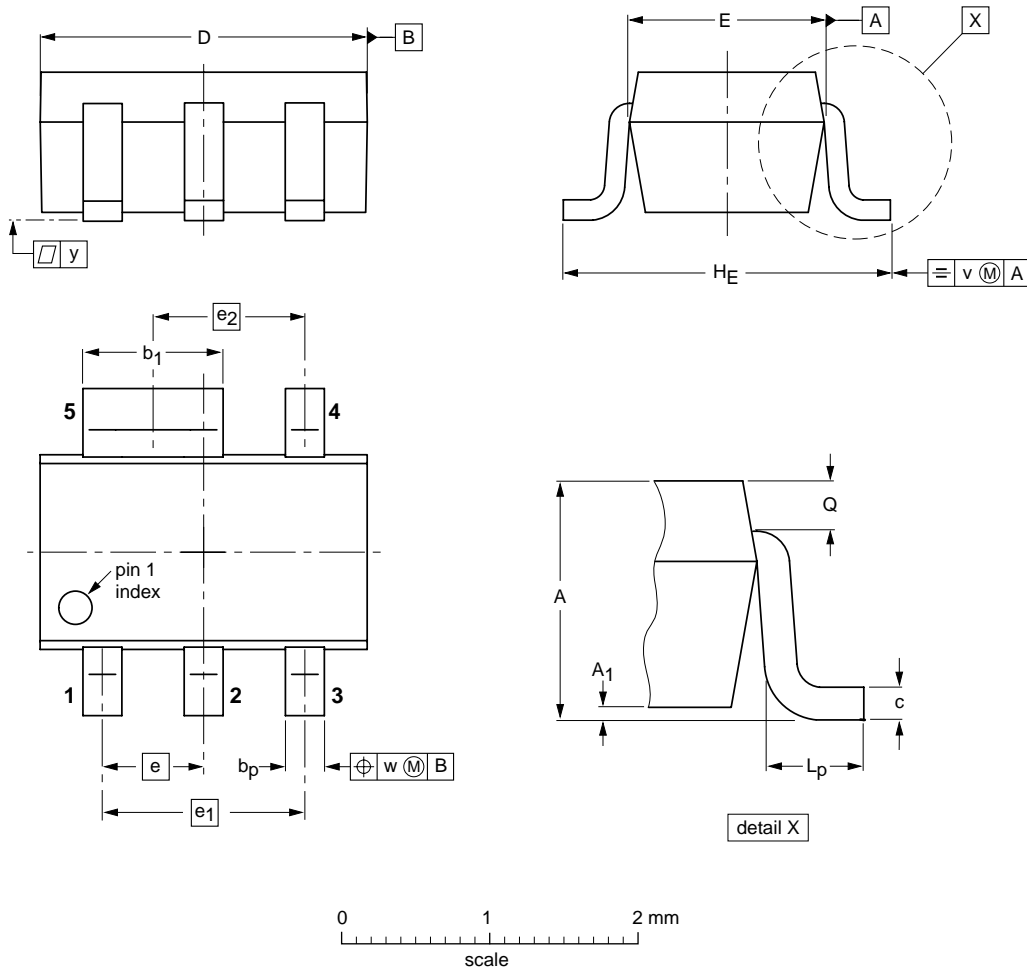
PACKAGE OUTLINE

Plastic surface mounted package; 5 leads

SOT551A

Package under development

Philips Semiconductors reserves the right to make changes without notice.



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	b ₁	c	D	E	e	e ₁	e ₂	H _E	L _p	Q	v	w	y
mm	1.1 0.9	0.1	0.3 0.2	0.8 1.0	0.25 0.10	2.2 1.8	1.35 1.15	0.65	1.3	0.975	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT551A						1999-05-07

MMIC variable gain amplifier

BGA2031

DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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NOTES

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NOTES

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